# **DEPARTMENT OF CIVIL ENGINEERING**





# VIRTUAL SMART STRUCTURES AND DYNAMICS LAB

# **EXPERIMENT 6 (SIMULATION)**

# Shear Lag Effect in Electro-Mechanical Impedance (EMI) Technique

## **OBJECTIVES**

This simulation based experiment is designed to teach the concept of shear lag in piezo based sensing/actuation operating through the medium of a bonding layer. The effect of shear lag on EMI signatures is studied with the aid of analytical models.

## **OVERVIEW**

The phenomenon of difference in the strain induced in the PZT patch from that in the host structure is called as shear lag effect. Figure 1 illustrates the process of actuation of a PZT patch by application of external voltage. As can be seen from the figure, the displacement induced on the surface of the host structure( $\mu_0$ ) is lesser than that in the PZT patch ( $\mu_0$ ) more about shear lag effect, the user may refer the doctoral thesis of Dr.Sumedha Moharana (http://web.iitd.ac.in/~sbhalla/thesispdf/sumedha.pdf).

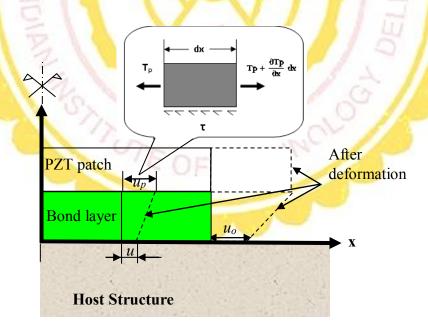


Figure 1: Principle of integrated SHM and energy harvesting

#### EXPERIMENTAL PROCEDURE

The simulations in this experiment are based on the analytical model developed by Dr.SumedhaMoharana. A host structure considered in this experiment on which the PZT patch is attached using epoxy adhesive as shown in Figure 2. The phenomenon of shear lag can be visualized with the help of animation as illustrated in Figure 2. The user can then derive simulated signatures for various bonding conditions, plot them in excel and visualize the effect of shear lag.

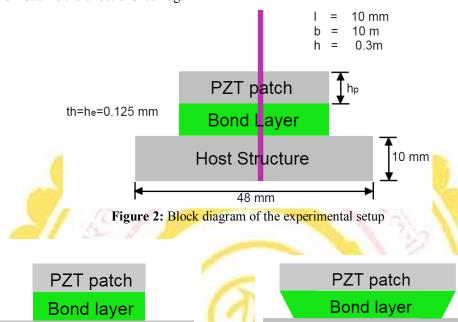


Figure 3: System in (a) Undeformed condition (b) After deformation

Host Structure

(b)

The deformation of the host structure is slower than the PZT patch and the bond layer.

## REFERENCES

- Bhalla, S. and Moharana, S. (2013), "A Refined Shear Lag Model for Adhesively Bonded Piezo-Impedance Transducers" <u>Journal of Intelligent Material Systems and Structures</u>, Vol. 24, No. 1 (Jan), pp. 33-48. DOI: 10.1177/1045389X12457837
- 2. Moharana, S. and Bhalla, S. (2014), "A Continuum Based Modelling Approach for Adhesively Bonded Piezo-Transducers for EMI Technique" <u>International Journal of Solids and Structures</u>, Vol. 51, No. 6 (Mar), pp. 1299-1310. DOI: 10.1016/j.ijsolstr.2013.12.022
- 3. Link to the thesis of Dr.Sumedha Mohrana.

Host Structure

(a)

4. <u>Literature on piezoelectric sensors</u>.